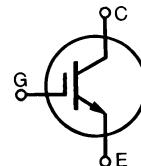


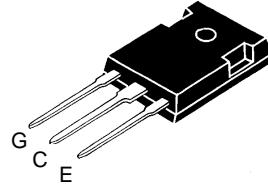
Low $V_{CE(sat)}$ IGBT High speed IGBT

IXGH 10 N100
IXGH 10 N100A

V_{CES}	I_{C25}	$V_{CE(sat)}$
1000 V	20 A	3.5 V
1000 V	20 A	4.0 V



TO-247 AD



G = Gate,
E = Emitter,
C = Collector,
TAB = Collector

Symbol	Test Conditions	Maximum Ratings		
V_{CES}	$T_J = 25^\circ\text{C}$ to 150°C	1000	V	
V_{CGR}	$T_J = 25^\circ\text{C}$ to 150°C ; $R_{GE} = 1 \text{ M}\Omega$	1000	V	
V_{GES}	Continuous	± 20	V	
V_{GEM}	Transient	± 30	V	
I_{C25}	$T_C = 25^\circ\text{C}$	20	A	
I_{C90}	$T_C = 90^\circ\text{C}$	10	A	
I_{CM}	$T_C = 25^\circ\text{C}, 1 \text{ ms}$	40	A	
SSOA (RBSOA)	$V_{GE} = 15 \text{ V}$, $T_{VJ} = 125^\circ\text{C}$, $R_G = 150 \Omega$ Clamped inductive load, $L = 300 \mu\text{H}$	$I_{CM} = 20$ @ $0.8 V_{CES}$	A	
P_c	$T_C = 25^\circ\text{C}$	100	W	
T_J		-55 ... +150	$^\circ\text{C}$	
T_{JM}		150	$^\circ\text{C}$	
T_{stg}		-55 ... +150	$^\circ\text{C}$	
M_d	Mounting torque (M3)	1.13/10	Nm/lb.in.	
Weight		6	g	
Maximum lead temperature for soldering 1.6 mm (0.062 in.) from case for 10 s		300	$^\circ\text{C}$	

Symbol	Test Conditions	Characteristic Values		
		($T_J = 25^\circ\text{C}$, unless otherwise specified)	min.	typ.
BV_{CES}	$I_C = 3 \text{ mA}$, $V_{GE} = 0 \text{ V}$	1000		V
$V_{GE(th)}$	$I_C = 250 \mu\text{A}$, $V_{CE} = V_{GE}$	2.5		V
I_{CES}	$V_{CE} = 0.8 \cdot V_{CES}$ $V_{GE} = 0 \text{ V}$	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$	250	μA 1 mA
I_{GES}	$V_{CE} = 0 \text{ V}$, $V_{GE} = \pm 20 \text{ V}$		± 100	nA
$V_{CE(sat)}$	$I_C = I_{C90}$, $V_{GE} = 15 \text{ V}$	10N100 10N100A	3.5 4.0	V

- International standard package JEDEC TO-247 AD
- 2nd generation HDMOS™ process
- Low $V_{CE(sat)}$
 - for low on-state conduction losses
- High current handling capability
- MOS Gate turn-on
 - drive simplicity
- Voltage rating guaranteed at high temperature (125°C)

Applications

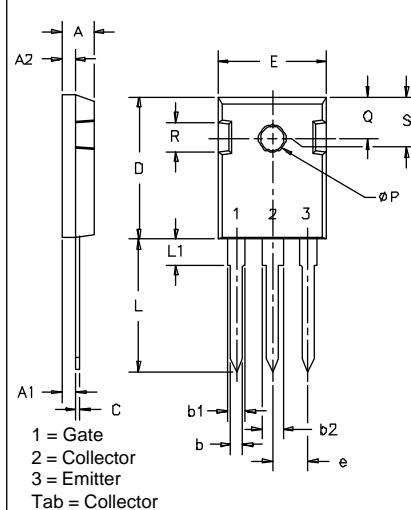
- AC motor speed control
- DC servo and robot drives
- DC choppers
- Uninterruptible power supplies (UPS)
- Switch-mode and resonant-mode power supplies

Advantages

- Easy to mount with 1 screw (isolated mounting screw hole)
- High power density

Symbol	Test Conditions	Characteristic Values			
		($T_J = 25^\circ\text{C}$, unless otherwise specified)	min.	typ.	max.
g_{fs}	$I_C = I_{C90}$; $V_{CE} = 10 \text{ V}$, Pulse test, $t \leq 300 \mu\text{s}$, duty cycle $\leq 2\%$	4	8	S	
C_{ies} C_{oes} C_{res}	$V_{CE} = 25 \text{ V}$, $V_{GE} = 0 \text{ V}$, $f = 1 \text{ MHz}$	750		pF	
		150		pF	
		30		pF	
Q_g Q_{ge} Q_{gc}	$I_C = I_{C90}$, $V_{GE} = 15 \text{ V}$, $V_{CE} = 0.5 V_{CES}$	52	70	nC	
		13	25	nC	
		24	45	nC	
$t_{d(on)}$ t_{ri} $t_{d(off)}$ t_{fi} E_{off}	Inductive load, $T_J = 25^\circ\text{C}$ $I_C = I_{C90}$, $V_{GE} = 15 \text{ V}$, $L = 300 \mu\text{H}$, $V_{CE} = 0.8 V_{CES}$, $R_G = R_{off} = 150 \Omega$ Remarks: Switching times may increase for V_{CE} (Clamp) $> 0.8 \cdot V_{CES}$, higher T_J or increased R_G	100		ns	
		200		ns	
		550	900	ns	
		800		ns	10N100
		500		ns	10N100A
$t_{d(on)}$ t_{ri} E_{on} $t_{d(off)}$ t_{fi} E_{off}	Inductive load, $T_J = 125^\circ\text{C}$ $I_C = I_{C90}$, $V_{GE} = 15 \text{ V}$, $L = 300 \mu\text{H}$ $V_{CE} = 0.8 V_{CES}$, $R_G = R_{off} = 150 \Omega$ Remarks: Switching times may increase for V_{CE} (Clamp) $> 0.8 \cdot V_{CES}$, higher T_J or increased R_G	100		ns	
		200		ns	
		1.1		mJ	
		600	1000	ns	
		1250	2000	ns	10N100
R_{thJC} R_{thCK}		950	1000	ns	10N100A
		5.0		mJ	10N100
		2.5		mJ	10N100A
				1.2 K/W	
			0.25	K/W	

TO-247 AD Outline



SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.185	.209	4.7	5.3
A ₁	.087	.102	2.2	2.54
A ₂	.059	.098	2.2	2.6
b	.040	.055	1.0	1.4
b ₁	.065	.084	1.65	2.13
b ₂	.113	.123	2.87	3.12
C	.016	.031	.4	.8
D	.819	.845	20.80	21.46
E	.610	.640	15.75	16.26
e	.215	BSC	5.45	BSC
L	.780	.800	19.81	20.32
L ₁		.177		4.50
ØP	.140	.144	3.55	3.65
Q	.212	.244	5.4	6.2
R	.170	.216	4.32	5.49
S	.242	BSC	6.15	BSC

IXGH 10N100 and IXGH 10N100A characteristic curves are located on the IXGH 10N100U1 and IXGH 10N100AU1 data sheets.